

FIG. 1A

TTA

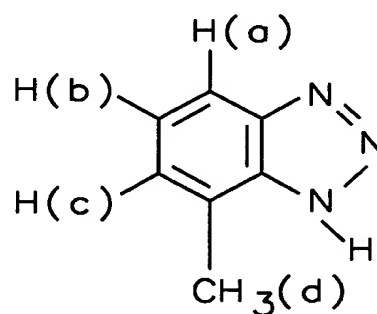
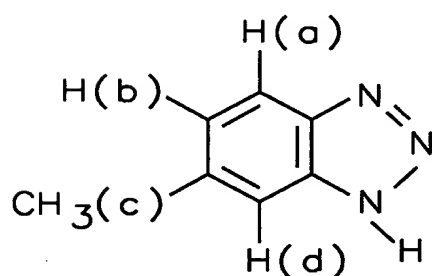
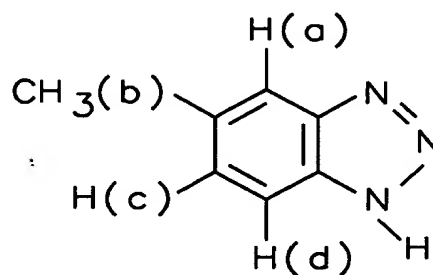
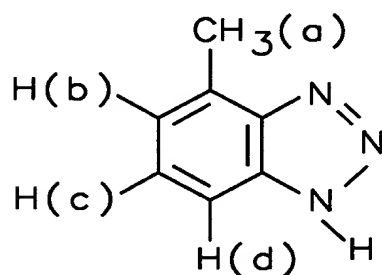


FIG. 1B

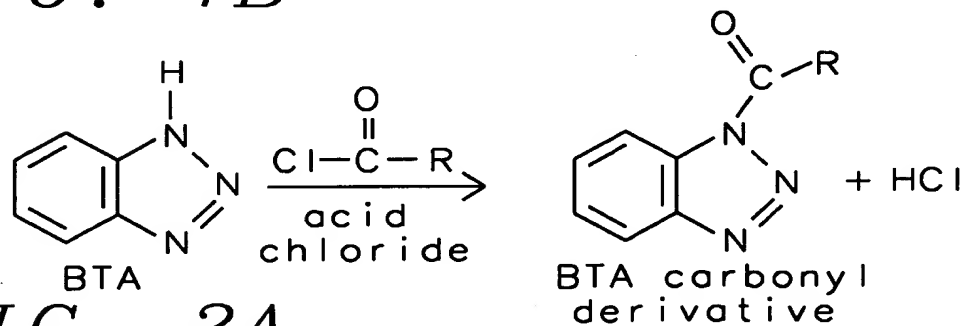


FIG. 2A

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2/5

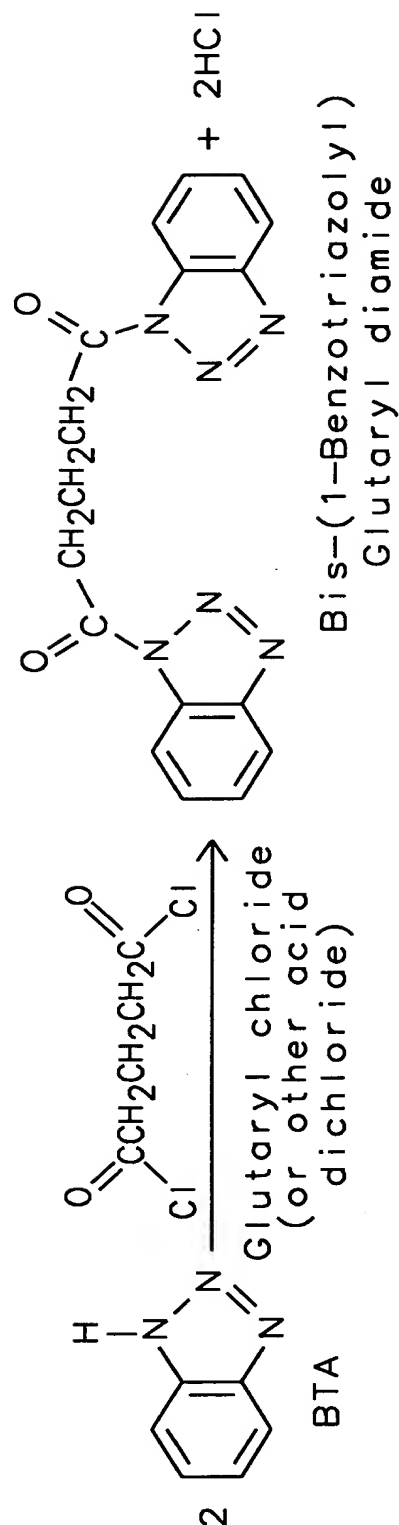
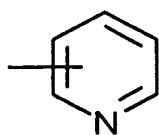
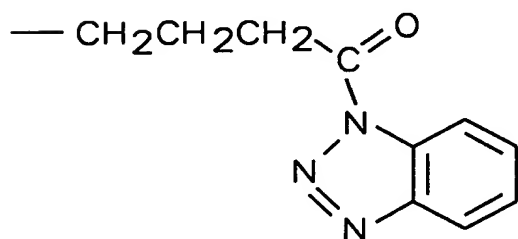
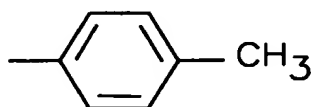


FIG. 2B

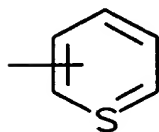
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3/5

WHERE  $R =$  —CH<sub>3</sub>  
—CH<sub>2</sub>CH<sub>3</sub>  
—CH<sub>2</sub>CH<sub>2</sub>CH<sub>3</sub>  
—CH<sub>2</sub>CH<sub>2</sub>CH<sub>2</sub>CH<sub>3</sub>  
—C(CH<sub>3</sub>)<sub>3</sub>



2-pyridyl,  
3-pyridyl,  
or  
4-pyridyl



2 thiophenyl  
or  
3 thiophenyl

FIG. 2C

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I. Before CMP, with slurry, Flow on the water  
where  $\delta\delta$  = new additive

II. During CMP, due to the formation of the protective film, removal rate becomes different with  $R1 > R2 \sim R3$

III. After CMP, the Cu surface is protected by the passive film

FIG. 3

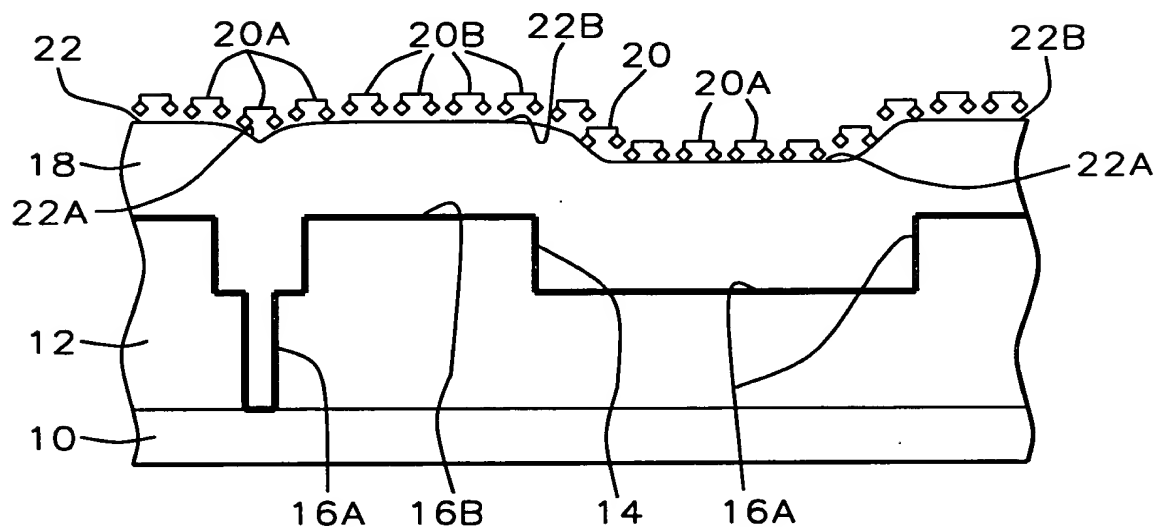


FIG. 4A

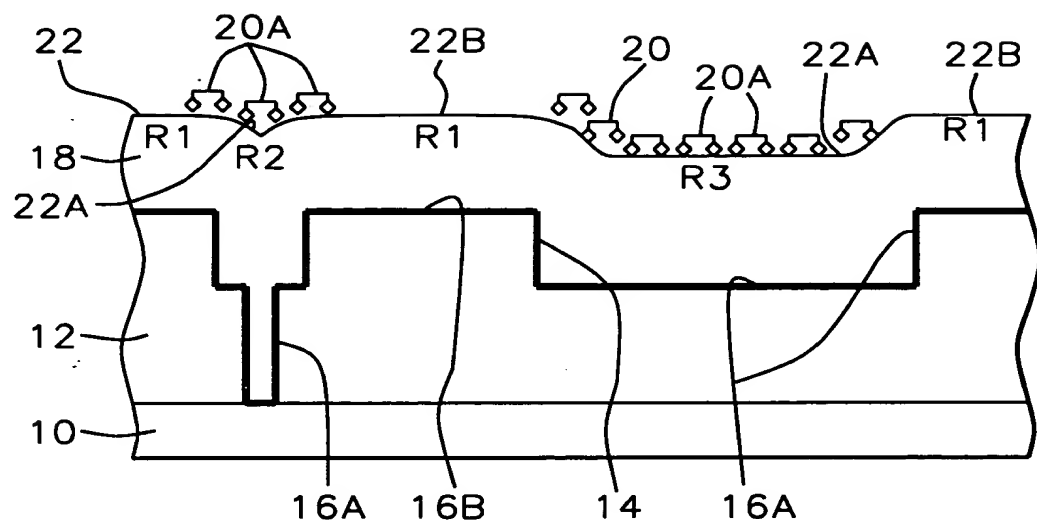


FIG. 4B

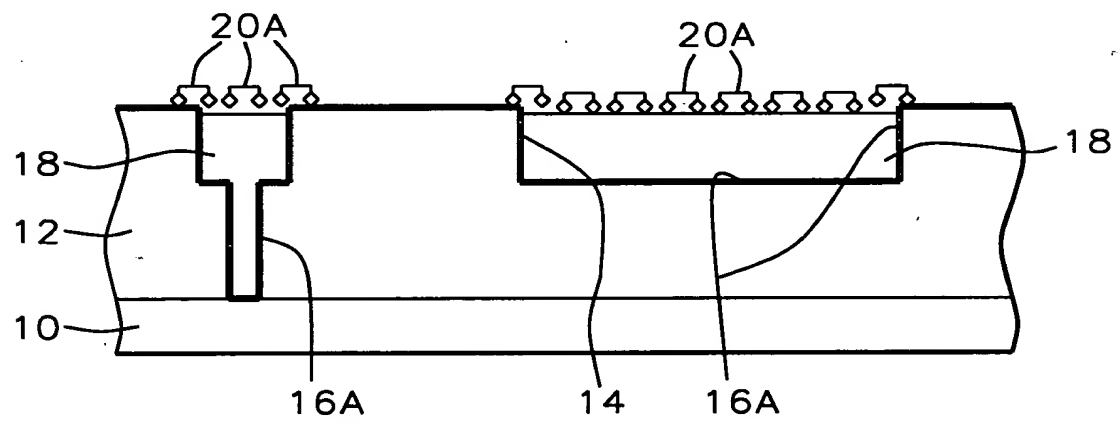


FIG. 4C

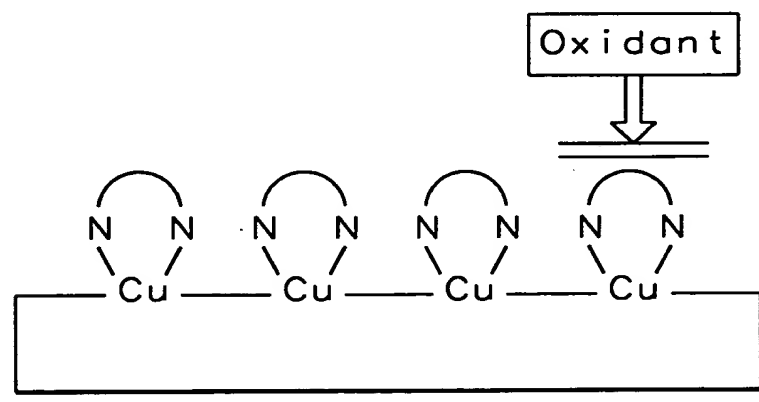


FIG. 5